TIP29, A, B, C (NPN), TIP30, A, B, C (PNP)

Complementary Silicon Plastic Power Transistors

Designed for use in general purpose amplifier and switching applications. Compact TO-220 package.

Features

• These Devices are Pb-Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage TIP29G, TIP30G TIP29AG, TIP30AG TIP29BG, TIP30BG TIP29CG, TIP30CG	V _{CEO}	40 60 80 100	Vdc
Collector – Base Voltage TIP29G, TIP30G TIP29AG, TIP30AG TIP29BG, TIP30BG TIP29CG, TIP30CG	V _{CB}	40 60 80 100	Vdc
Emitter – Base Voltage	V_{EB}	5.0	Vdc
Collector Current – Continuous	۱ _C	1.0	Adc
Collector Current – Peak	I _{CM}	3.0	Adc
Base Current	I _B	0.4	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	30 0.24	W W/°C
Total Power Dissipation @ T _A = 25°C Derate above 25°C	P _D	2.0 0.016	W W/°C
Unclamped Inductive Load Energy (Note 1)	E	32	mJ
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. This rating based on testing with L_C = 20 mH, R_{BE} = 100 $\Omega,\,V_{CC}$ = 10 V, I_C = 1.8 A, P.R.F = 10 Hz

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	4.167	°C/W

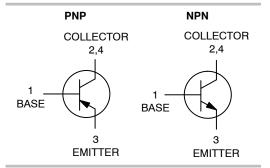
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

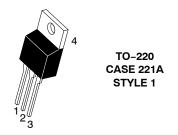


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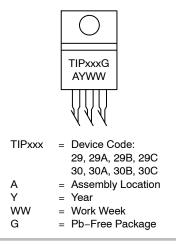
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1 AMPERE POWER TRANSISTORS COMPLEMENTARY SILICON 40, 60, 80, 100 VOLTS, 80 WATTS





MARKING DIAGRAM



ORDERING INFORMATION

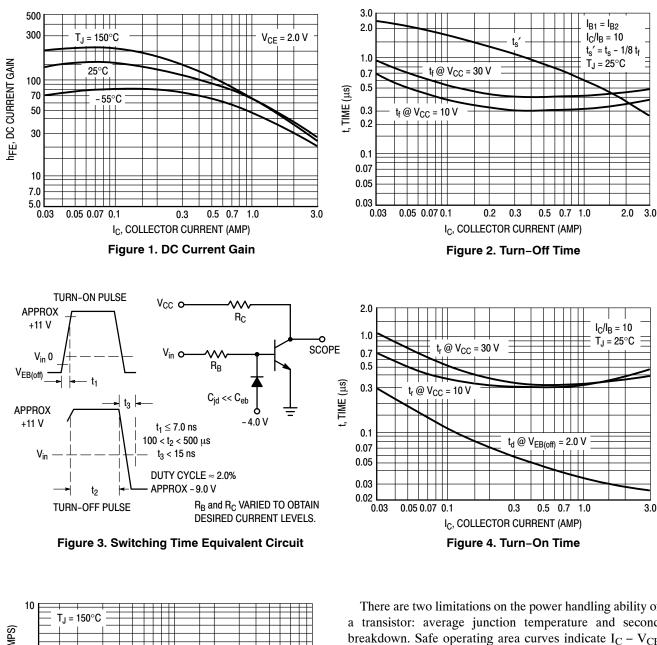
See detailed ordering and shipping information on page 4 of this data sheet.

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Min	Max	Unit
L			
V _{CEO(sus)}	40 60 80 100	- - - -	Vdc
I _{CEO}	-	0.3 0.3	mAdc
I _{CES}		200 200 200 200	μAdc
I _{EBO}		1.0	mAdc
h _{FE}	40 15	_ 75	-
V _{CE(sat)}	_	0.7	Vdc
V _{BE(on)}	_	1.3	Vdc
		<u>.</u>	•
f _T	3.0	_	MHz
h _{fe}	20	_	-
	ICEO ICES ICES IEBO IEBO VCE(sat) VBE(on)	$\begin{array}{c c c c c c } & 40 \\ & 60 \\ & 80 \\ & 100 \\ & & & \\$	$\left \begin{array}{cccccccccccccccccccccccccccccccccccc$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test conditions. 2. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0% 3. f_T = |h_{fe}| • f_{test}



IC, COLLECTOR CURRENT (AMPS) 3.0 ms dc 0.1 SECOND BREAKDOWN LIMITED THERMALLY LIMITED @ T_C = 25°C ms BONDING WIRE LIMITED TIP29, 30 CURVES APPLY BELOW TIP29A, 30A RATED V_{CEO} TIP29B, 30B 0.1 ∟ 1.0 TIP29C, 30C 4.0 20 10 40 100 V_{CF}, COLLECTOR-EMITTER VOLTAGE, (VOLTS)

Figure 5. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C - V_{CE} operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)} = 150^{\circ}C$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)}$ \leq 150°C. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

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ORDERING INFORMATION

Device	Package	Shipping				
TIP29G	TO-220 (Pb-Free)	50 Units / Rail				
TIP29AG	TO-220 (Pb-Free)	50 Units / Rail				
TIP29BG	TO-220 (Pb-Free)	50 Units / Rail				
TIP29CG	TO-220 (Pb-Free)	50 Units / Rail				
TIP30G	TO-220 (Pb-Free)	50 Units / Rail				
TIP30AG	TO-220 (Pb-Free)	50 Units / Rail				
TIP30BG	TO-220 (Pb-Free)	50 Units / Rail				
TIP30CG	TO-220 (Pb-Free)	50 Units / Rail				

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				4. MAX WIDTH FOR F102 DEVICE = 1.35MM					
	I	Γ I			INC	HES	MILLIM	ETERS	
				DIM	MIN.	MAX.	MIN.	MAX.	
	2 3			А	0.570	0.620	14.48	15.75	
<u> </u>	┟┰┟┟╌┙──┼			В	0.380	0.415	9.66	10.53	
⊢	₩+₩++			С	0.160	0.190	4.07	4.83	
	í lí	f I		D	0.025	0.038	0.64	0.96	
' z –	I I K			F	0.142	0.161	3.60	4.09	
	î î			G	0.095	0.105	2.42	2.66	
				н	0.110	0.161	2.80	4.10	
	¥ ₩	ü l		J	0.014	0.024	0.36	0.61	
V —	R —			ĸ	0.500	0.562	12.70 1.15	14.27	
G	J-	╼║╼		N	0.045	0.060	4.83	1.52 5.33	
Ŭ,	' → → D			Q	0.190	0.210	2.54	3.04	
_	N -			R	0.100	0.120	2.54	2.79	
				s	0.030	0.055	1.15	1.41	
				т	0.235	0.255	5.97	6.47	
				U U	0.000	0.050	0.00	1.27	
				v	0.045		1.15		
				z		0.080		2.04	
2. 3. 4. STYLE 5: PIN 1. 2. 3. 4. STYLE 9: PIN 1. 2. 3.	BASE PIN 1. COLLECTOR 2. EMITTER 3. COLLECTOR 4. GATE PIN 1. DRAIN 2. SOURCE 3. DRAIN 2. GATE PIN 1. CALL STYLE 10 GATE PIN 1. COLLECTOR 2. EMITTER 3.	BASE EMITTER COLLECTOR EMITTER ANODE CATHODE CATHODE CATHODE	2. 3. 4. STYLE 7: PIN 1. 2. 3. 4. STYLE 11: PIN 1. 2. 3.		E E	2. MA 3. GA 4. MA STYLE 8: PIN 1. CA 2. AN 3. EX 4. AN STYLE 12: PIN 1. MA 2. MA 3. GA	IN TERMINAL THODE DDE TERNAL TRIP DDE IN TERMINAL IN TERMINAL	2 2 /DELAY .2	

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 TO-220
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